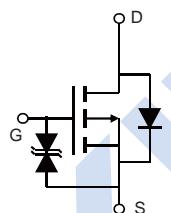
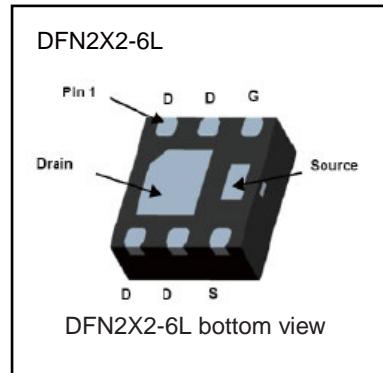


## P-channel MOSFET

## 2KJ7107DFN

## ■ Features

- $V_{DS}$  (V) = -20V
- $I_D$  = -6.0A
- Low threshold voltage
- Very fast switching
- Trench MOSFET technology
- 2 kV ElectroStatic Discharge (ESD) protection

■ Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$  Unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	-20	V
Gate-Source Voltage	$V_{GS}$	$\pm 8$	
Continuous Drain Current, $t \leq 5\text{ s}$ *1	$I_D$	-6.0	A
Pulsed Drain Current ( $t_p \leq 10\mu\text{s}$ )	$I_{DM}$	-14.4	
Power Dissipation *1 *2	$P_D$	1210	mW
		515	
Electrostatic Discharge Voltage *3	$V_{ESD}$	2000	V
Thermal Resistance, Junction- to-Ambient in free air *2 in free air; $t \leq 5\text{ s}$ *1	$R_{JA}$	244	°C/W
		104	
		64	
Junction Temperature	$T_J$	150	°C
Storage Temperature Range	$T_{stg}$	-55 to 150	

\*1. Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm<sup>2</sup>.

\*2. Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

\*3. HBM; C = 100 pF; R = 1.5 kΩ; Measured between all pins.

## P-channel MOSFET

## 2KJ7107DFN

■ Electrical Characteristics ( $T_A = 25^\circ\text{C}$  Unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{DSS}$	$I_D=-10\mu\text{A}, V_{GS}=0\text{V}$	-20			V
Zero Gate Voltage Drain Current	$I_{DS(0)}$	$V_{DS}=-20\text{V}, V_{GS}=0\text{V}$			-1	$\mu\text{A}$
		$V_{DS}=-20\text{V}, V_{GS}=0\text{V}, T_J = 150^\circ\text{C}$			-10	
Gate-Body Leakage Current	$I_{GSS}$	$V_{DS}=0\text{V}, V_{GS}=\pm 8\text{V}$			$\pm 10$	$\mu\text{A}$
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	-0.45		-0.95	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=-4.5\text{V}, I_D=-2\text{A}$		28	35	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}, I_D=-2\text{A}, T_J = 150^\circ\text{C}$			60	
		$V_{GS}=-2.5\text{V}, I_D=-1.5\text{A}$		42	60	
		$V_{GS}=-1.8\text{V}, I_D=-1\text{A}$		63	100	
Forward Transconductance	$g_{FS}$	$V_{DS}=-10\text{V}, I_D=-2\text{A}$		9		S
Input Capacitance	$C_{iss}$	$V_{GS}=0\text{V}, V_{DS}=-10\text{V}, f=1\text{MHz}$		804		$\text{pF}$
Output Capacitance	$C_{oss}$			95		
Reverse Transfer Capacitance	$C_{rss}$			66		
Total Gate Charge	$Q_g$	$V_{DS}=-10\text{V}, I_D=-2\text{A}, V_{GS} = -4.5\text{V}$		6.3	9.5	$\text{nC}$
Gate Source Charge	$Q_{gs}$			1.2		
Gate Drain Charge	$Q_{gd}$			0.9		
Turn-On Delay Time	$t_{d(on)}$	$V_{DS}=-10\text{V}, I_D=-2\text{A}, V_{GS} = -4.5\text{V}$		7		$\text{ns}$
Turn-On Rise Time	$t_r$			15		
Turn-Off Delay Time	$t_{d(off)}$			41		
Turn-Off Fall Time	$t_f$			14		
Maximum Body-Diode Continuous Current	$I_s$				-1.3	A
Diode Forward Voltage	$V_{SD}$	$I_{SD}=-0.5 \text{ A}, V_{GS}=0\text{V}$			-1.2	V

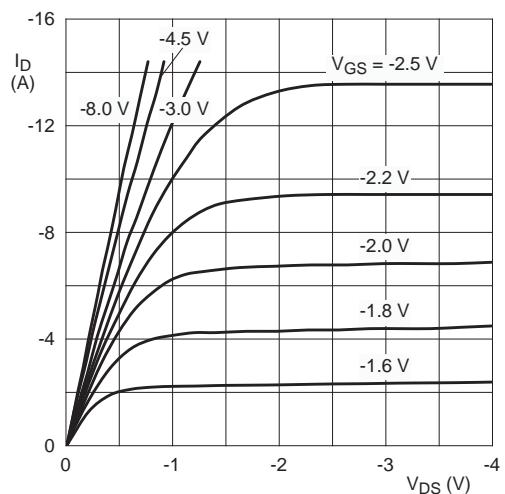
## ■ Marking

Marking	JAN
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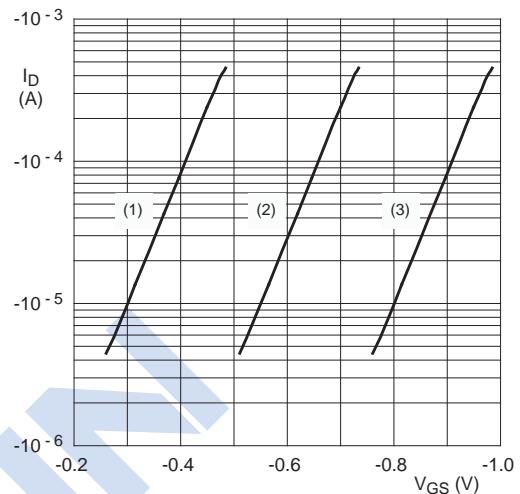
## P-channel MOSFET

## 2KJ7107DFN

## ■ Typical Characteristics

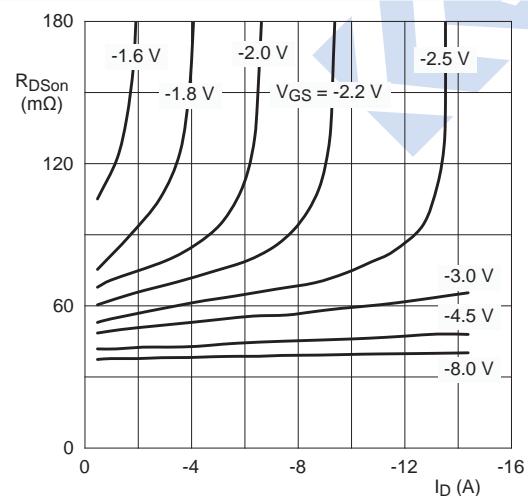
 $T_j = 25^\circ\text{C}$ 

**Fig. 1. Output characteristics: drain current as a function of drain-source voltage; typical values**

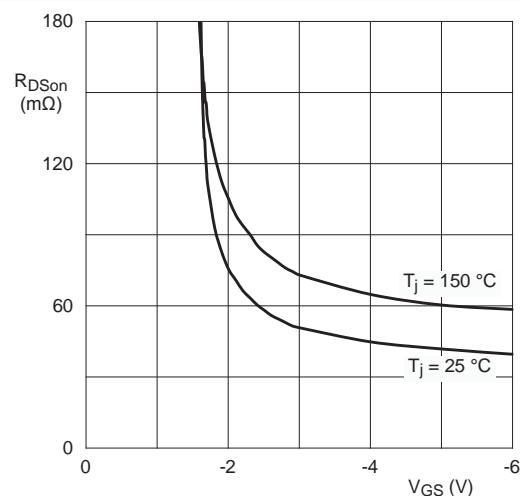
 $T_j = 25^\circ\text{C}; V_{DS} = -3\text{ V}$ 

- (1) minimum values
- (2) typical values
- (3) maximum values

**Fig. 2. Sub-threshold drain current as a function of gate-source voltage**

 $T_j = 25^\circ\text{C}$ 

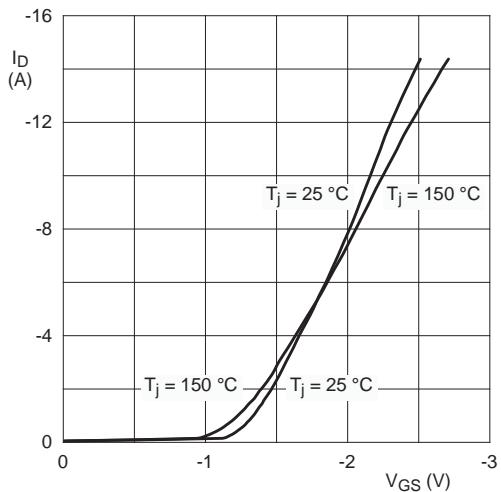
**Fig. 3. Drain-source on-state resistance as a function of drain current; typical values**

 $I_D = -2\text{ A}$ 

**Fig. 4. Drain-source on-state resistance as a function of gate-source voltage; typical values**

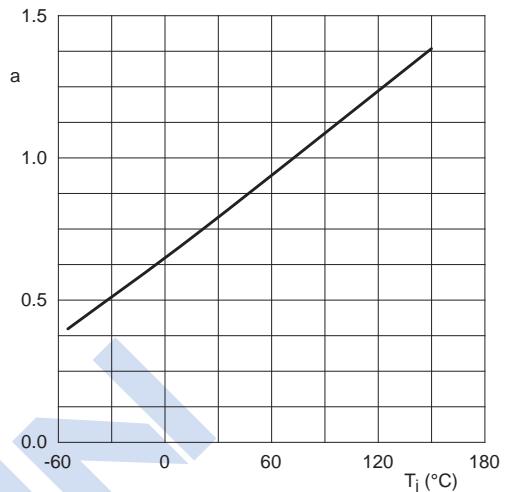
## P-channel MOSFET

## 2KJ7107DFN



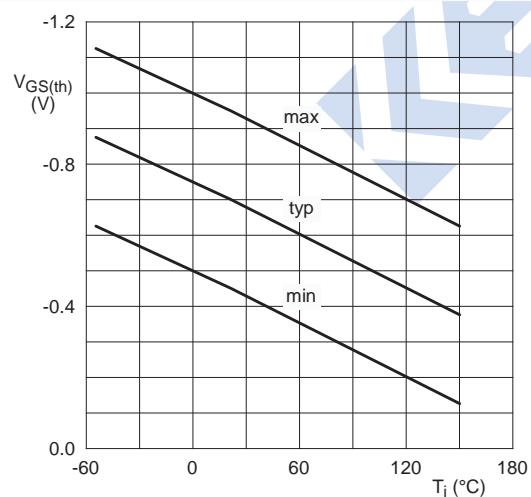
$V_{DS} > I_D \times R_{DSon}$

**Fig. 5. Transfer characteristics: drain current as a function of gate-source voltage; typical values**



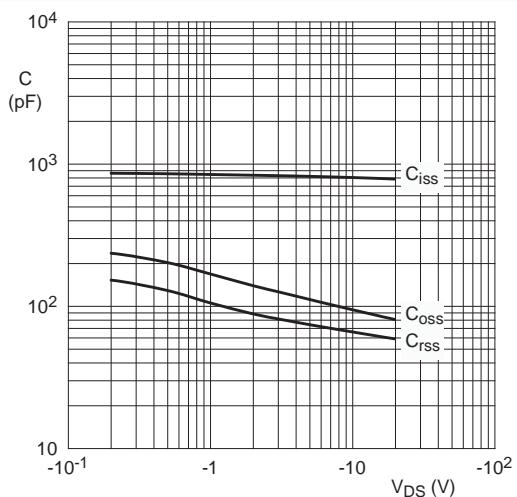
**Fig. 6. Normalized drain-source on-state resistance as a function of junction temperature; typical values**

$$a = \frac{R_{DSon}}{R_{DSon}(25^\circ\text{C})}$$



$I_D = -0.25 \text{ mA}; V_{DS} = V_{GS}$

**Fig. 7. Gate-source threshold voltage as a function of junction temperature**



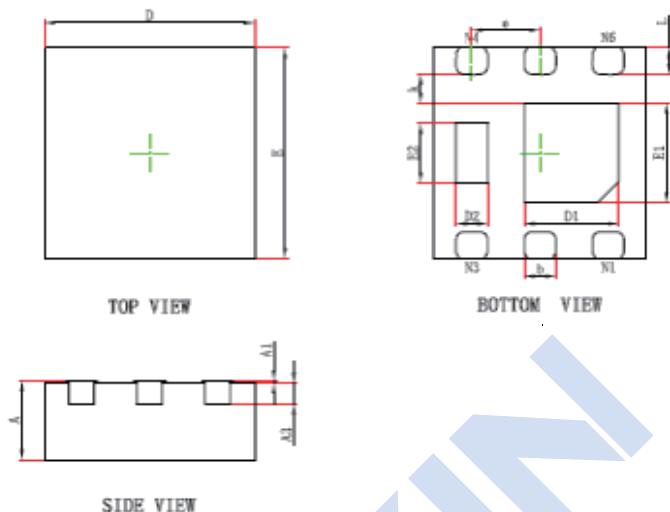
$f = 1 \text{ MHz}; V_{GS} = 0 \text{ V}$

**Fig. 8. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values**

## P-channel MOSFET

## 2KJ7107DFN

## ■ DFN2X2-6L Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A3	0.203REF.		0.008REF.	
D	1.924	2.076	0.076	0.082
E	1.924	2.076	0.076	0.082
D1	0.800	1.000	0.031	0.039
E1	0.850	1.050	0.033	0.041
D2	0.200	0.400	0.008	0.016
E2	0.460	0.660	0.018	0.026
k	0.200MIN.		0.008MIN.	
b	0.250	0.350	0.010	0.014
e	0.650TYP.		0.026TYP.	
L	0.174	0.326	0.007	0.013

**Notes**

1. All dimensions are in millimeters.
2. Tolerance  $\pm 0.10\text{mm}$  (4 mil) unless otherwise specified
3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
4. Dimension L is measured in gauge plane.
5. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.